

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC9301xxxxMR-G

Typical Mass: 16 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.833	Silicon	52100	7440-21-3
Leadframe	5.503	Copper	343900	7440-50-8
	0.022	Tin	1400	7440-31-5
	0.021	Zinc	1300	7440-66-6
	0.024	Chromium	1500	7440-47-3
	0.325	Silver	20300	7440-22-4
Die attach	0.049	Silver	3000	7440-22-4
	0.009	Epoxy	600	—
Bonding wire	0.050	Gold	3100	7440-57-5
Resin	7.164	Silica	447700	60676-86-0
	0.681	Epoxy Resin	42600	—
	0.573	Phenol Resin	35800	—
	0.407	Metal Hydroxide	25500	—
Plating	0.340	Tin	21300	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."